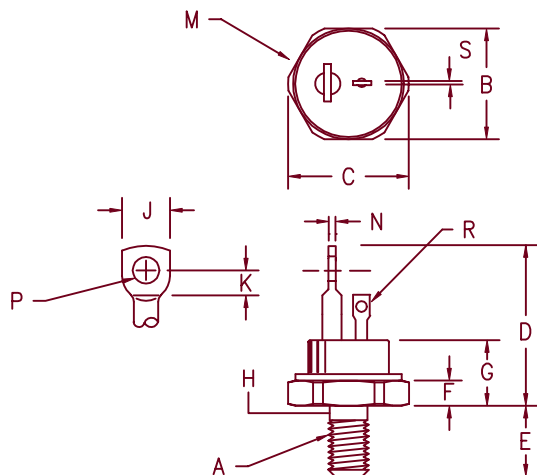


Silicon Controlled Rectifier Series 40C



Note 1: 1/4-28 UNF-3A

Note 2: Full thread within 2 1/2 threads

Dim.	Inches		Millimeter		Notes
	Minimum	Maximum	Minimum	Maximum	
A	---	---	---	---	1
B	.677	.685	17.20	17.40	
C	---	.770	---	19.56	
D	1.200	1.250	30.48	31.75	
E	.427	.447	10.84	11.35	
F	.115	.155	2.92	3.94	
G	---	.515	---	13.08	
H	---	.249	---	6.32	2
J	.200	.300	5.08	7.62	
K	.120	---	3.05	---	
M	---	.667	---	16.94	Dia.
N	.065	.085	1.65	2.15	
P	.145	.155	3.68	3.93	Dia.
R	.055	.065	1.40	1.65	
S	.025	.030	.64	.76	

TO-208AC (TO-65)

Microsemi
Catalog Number

Forward & Reverse
Repetitive Blocking
VDRM, VRRM

Reverse Transient
Blocking

40C20B
40C40B
40C60B
40C80B
40C100B
40C120B

200
400
600
800
1000
1200

300
500
700
900
1100
1300

To specify dv/dt other than 200V/usec., contact factory.

- dv/dt-200 V/usec
- 1000 Amperes surge current
- Economical for medium power applications
- Compact TO-208AC package

Electrical Characteristics

Max. RMS on-state current
Max. average on-state cur.
Max. peak on-state voltage
Max. holding current
Max. peak one cycle surge current
Max. I²t capability for fusing

I_{T(RMS)} 63 Amps
I_{T(AV)} 40 Amps
V_{TM} 3.0 Volts
I_H 200 mA
I_{TSM} 1000 A
I²t 4100A²S

T_C = 102°C
T_C = 102°C
I_{TM} = 500 A(peak)
T_C = 120°C, 60Hz
t = 8.3 ms

Thermal and Mechanical Characteristics

Operating junction temp range
Storage temperature range
Maximum thermal resistance
Typical thermal resistance
Mounting torque
Weight

T_J
T_{STG}
R_{ΘJC}
R_{ΘCS}

-65°C to 125°C
-65°C to 150°C
0.35°C/W Junction to case
0.20°C/W Case to sink
25-30 inch pounds
0.56 ounces (16 grams) typical

8-31-00 Rev. 2



COLORADO

Microsemi

800 Hoyt Street
Broomfield, CO. 80020
PH: (303) 469-2161
FAX: (303) 466-3775
www.microsemi.com

40C

$T_J = 25^\circ\text{C}$ unless otherwise indicated

Switching

Critical rate of rise of on-state current (note 1)	di/dt	200A/usec.	$T_J = 125^\circ\text{C}$
Typical delay time (note 1)	t_d	3.0 usec.	
Typical circuit commuted turn-off time (note 2)	t_q	100 usec.	$T_J = 125^\circ\text{C}$

Note 1: $I_{TM} = 50\text{A}$, $V_D = V_{DRM}$. $GT = 12\text{V}$ open circuit, 20 ohm–0.1 usec. rise time

Note 2: $I_{TM} = 50\text{A}$, $di/dt = 5\text{A/usec.}$, V_R during turn-off interval = 50V min.,
reapplied $dv/dt = 20\text{V/usec.}$, linear to rated V_{DRM} , $V_{GT} = 0\text{V}$

Triggering

Max. gate voltage to trigger	V_{GT}	3.0V	$T_J = 125^\circ\text{C}$
Max. nontriggering gate voltage	V_{GD}	0.25V	
Max. gate current to trigger	I_{GT}	100mA	
Max. peak gate power	P_{GM}	10W	$t_p = 10 \text{ usec.}$
Average gate power	$P_{G(AV)}$	1.0W	
Max. peak gate current	I_{GM}	3.0A	
Max. peak gate voltage (forward)	V_{GM}	20V	
Max. peak gate voltage (reverse)	V_{GM}	10V	

Blocking

Max. leakage current	I_{DRM}	6mA	$T_J = 125^\circ\text{C} \ \& \ V_{DRM}$
Max. reverse leakage	I_{RRM}	6mA	$T_J = 125^\circ\text{C} \ \& \ V_{RRM}$
Critical rate of rise of off-state voltage	dv/dt	200V/usec.	$T_J = 125^\circ\text{C}$

40C

Figure 1
Typical Forward On-State Characteristics

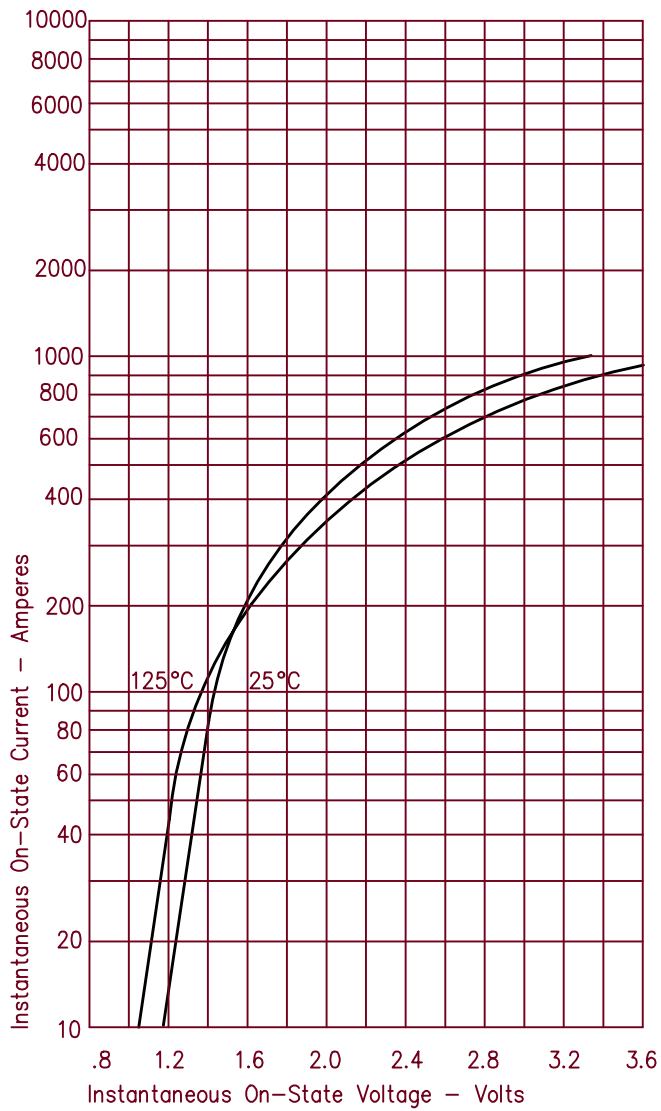


Figure 3
Maximum Power Dissipation

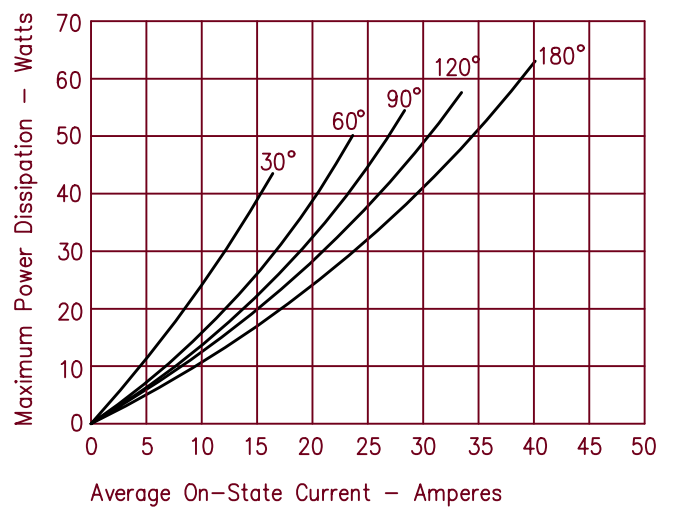


Figure 4
Transient Thermal Impedance

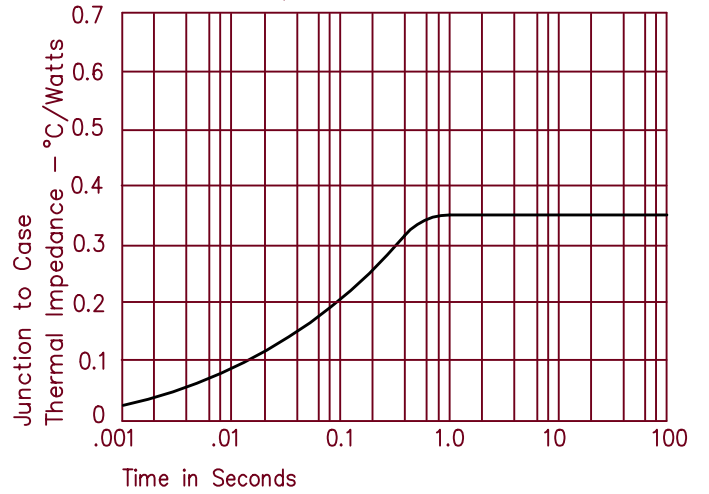


Figure 2
Forward Current Derating

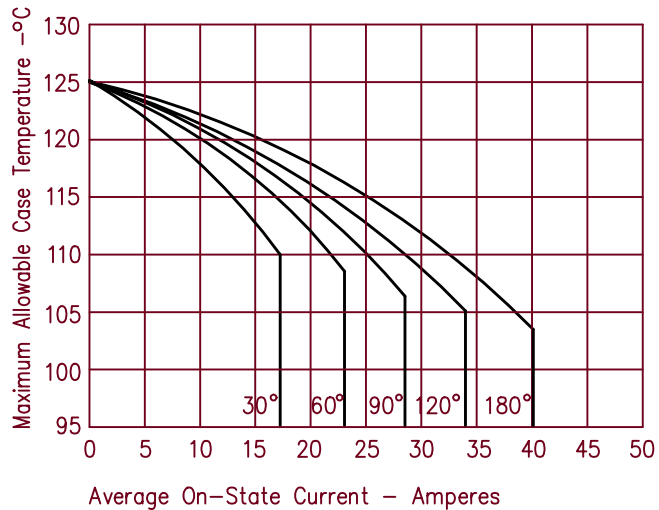


Figure 5
Maximum Nonrepetitive Surge Current

